



Lead Free No-clean Solder Paste

S3X58-M406D

■ Feature

- 1) A combination of binary eutectic alloy composed of Tin and Silver, and Koki's unique halide free no-clean flux realizes soldering performances equivalent to conventional no-clean solder pastes including wettability.
- 2) Carefully selected flux chemistry ensures unique low voids formation and powerful wetting.
- 3) Specially developed flux system ensures both extremely high reliability and superior solder wettability.
- 4) Extremely long tack time offers wide process window.
- 5) Low color flux residue offers superior cosmetic appearance.

■ Specifications

Application		Dispensing	
Products		S3X58-M406D	
Alloy	Composition (%)	Sn3Ag0.5Cu	
	Shape	Spherical	
	Particle size (μm)	20 – 38	
	Melting point (°C)	217 - 218	
Flux	Halide content (%)	0.0	
	Surface insulation resistance * ¹	Initial value (Ω)	$> 1 \times 10^{13}$
		After humidification (Ω)	$> 1 \times 10^{11}$
	Aqueous solution resistivity* ² (Ω cm)	$> 5 \times 10^4$	
Flux type	ROL0		
Product	Flux content (%)	13	
	Viscosity* ³ (Pa.S)	120	
	Copper plate corrosion* ⁴	Passed	
	Solder spread factor (%)	> 85	
	Tack time	> 24 hours	
Shelf life (below 10°C)	3 months		

1. SIR40°C × 90%RH × 96Hr
2. Aqueous solution resistivityIn accordance with MIL specifications.
3. ViscosityMalcom spiral type viscometer, PCU-2 at 25°C 10rpm
4. Copper plate corrosionIn accordance with JIS.

*Specifications are subject to change

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